Docket No. 251598US0

IN RE APPLICATION OF: Yukio HOSAKA, et al.

SERIAL NO: 10/820,123 FILED:

April 8, 2004

ABRASIVE PAD, METHOD AND METAL MOLD FOR MANUFACTURING THE SAME, AND FOR:

SEMICONDUCTOR WAFER POLISHING METHOD

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

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Transmitted herewith is an amendment in the above-identified application.

No additional	fee is	required	
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- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- ☐ Additional documents filed herewith:

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS		RATE		CALCULATIONS
TOTAL	22	MINUS	24	0	х	\$50	=	\$0.00
INDEPENDENT	2	MINUS	3	0	х	\$210	=	\$0.00
APPLICATION SIZE		MINUS	100	0 (each addtl. 50 sheets)	x	\$260	=	\$0.00
☐ MULTIPLE DEPENDENT CLAIMS + \$370 =						=	\$0.00	
TOTAL OF ABOVE CALCULATIONS					NS	\$0.00		
		☐ Reduction by 50% for filing by Small Entity					\$0.00	
TOTAL						\$0.00		

Α	check	in	the	amount	of	\$0.00	is	attached.

- Online credit card payment is being made to cover the fees in the amount of \$0.00
- Please charge any additional Fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030.

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